

**IN THE SPECIFICATION:**

The specification as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~striketrough~~.

Please REPLACE the paragraph number [0007] with the following replacement paragraph [0007]:

**[0007]** As shown in Table 1, with the increasing recording capacity, the pit size and track pitch decrease and technologies to make the pit size and track pitch much smaller are being developed. Here, BD indicates a ~~blu-ray disc~~BLU-RAY DISC.

Please REPLACE the paragraph number [0012] with the following replacement paragraph [0012]:

**[0012]** However, the wavelength of the laser beam and the numerical aperture have limitations and thus achieving even higher density and higher capacity recording in discs beyond the generation of the ~~blu-ray disc~~BLU-RAY DISC (BD) is difficult. Accordingly, a method using an electronic beam having a short wavelength instead of a laser beam are being newly researched and developed. Thus, new research and development is necessary to satisfy the high density and high capacity recording requirement.

Please REPLACE the paragraph number [0016] with the following replacement paragraph [0016]:

**[0016]** According to an aspect of the present invention, the heat absorption layer ~~is formed of~~includes an alloy layer.

Please REPLACE the paragraph number [0051] with the following replacement paragraph [0051]:

**[0051]** When the stamper 30 is separated ~~form~~from the separation layer 20, the separation

layer 20 may not be removed completely and part of the separation layer 20 may remain on the second dielectric layer 13 or on the electrode layer 27. However, even when part of the separation layer 20 remains on either side, the photoresist can be removed easily such that there is no particular difficulty in the manufacturing process. Also, when the separation layer 20 is formed of, for example, a liquid photoresist, the surface of the separation layer 20 is very smooth and the surface shape of this separation layer 20 is directly transferred to the stamper 30. Accordingly, there is an advantage in that the surface roughness of the stamper 30 is greatly reduced.